

NOV 0 2 2004

Sheet 1 of 1

FORM PTO-1449 INFORMATION DISCLOSURE STATEMENT				ATTY DOCKET NO. 51833		SERIAL NO. 10/816,627	
				APPLICANT(S): Beica et al.			
				FILING DATE: 04/02/2004		ART UNIT: 2812	
UNITED STATES PATENT DOCUMENTS							
EXAM. INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUB CLASS	FIL. DATE IF APPR
CK	AA	4,440,608	04/03/1984	Opaskar et al.			
CK	AB	5,646,068	07/08/1997	Wilson et al.			
CK	AC	5,854,514	12/29/1998	Roldan et al.			
CK	AD	5,990,564	11/23/1999	Degani et al.			
CK	AE	6,005,292	12/21/1999	Roldan et al.			
CK	AF	6,099,713	08/08/2000	Yanada et al.			
CK	AG	6,107,180	08/22/2000	Munroe et al.			
CK	AH	6,127,253	10/03/2000	Roldan et al.			
CK	AI	6,224,690	05/01/2001	Andricacos et al.			
CK	AJ	6,436,269	08/20/2002	Opaskar et al.			
CK	AK	6,436,730	08/20/2002	Melton et al.			
CK	AL	6,458,264	10/01/2002	Kunze et al. Moramatsu et al.			
CK	AM	6,476,494	11/05/2002	Hur et al.			
CK	AN	6,527,840	03/04/2003	Igarashi et al.			
CK	AO	6,607,653	08/19/2003	Nishikawa et al. Tsuji et al.			
CK	AP	2002/0127847 A1	09/12/2002	Alling et al.			
CK	AQ	2003/024822 A1	02/06/2003	Steinius et al.			
FOREIGN PATENT DOCUMENTS							
		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRAN YES/NO
CK	BA	1 001 054	05/17/2000	Europe			
CK	BB	0 854 206	08/16/2001	Europe			
CK	BC	9-143786	06/03/1997	Japan			
CK	BD	WO 01/02627	01/11/2001	International			
OTHER DOCUMENTS (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)							
CK	CA	Karim et al.; "Lead-Free Solder Bump Technologies for Flip-Chip Packaging Applications"; 2001 International Symposium on Microelectronics; pp. 581-583.					
CK	CB	Patent Abstracts of Japan, Vol. 2000, No. 23; 10 February 2001 & JP 2001 164396 A (Ishihara Chem. Co. Ltd.; Daiwa Kasei Kenkyusho: KK).					
Examiner: <i>Christy Karsick</i>				Date: 1/6/06			

KEM
8/31/08